

#### AMP-LATCH | AMP-LATCH Universal Headers

TE Internal #: 102153-4

AMP-LATCH Universal Headers, Ribbon Cable Connectors, Board-to-Board, 20 Position, .1 in [2.54 mm] Centerline, Vertical, Through

Hole - Solder, 2 Row

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Connector System: Board-to-Board

Number of Positions: 20

Centerline (Pitch): 2.54 mm [ .1 in ]
PCB Mount Retention: Without

PCB Mount Retention Type: Screw Mount

All AMP-LATCH UNIVERSAL HEADERS (525)

## **Features**

### **Product Type Features**

| Connector Type                     | Header                         |
|------------------------------------|--------------------------------|
| Ribbon Cable Connector Header Type | Universal Ejection Pin Headers |
| Connector Product Type             | Connector Assembly             |
| Connector System                   | Board-to-Board                 |
| Connector & Housing Type           | Receptacle                     |
| Connector & Contact Terminates To  | Printed Circuit Board          |
| Configuration Features             |                                |
| Number of Positions                | 20                             |
| PCB Mount Orientation              | Vertical                       |
| Number of Rows                     | 2                              |
| Electrical Characteristics         |                                |

 $5000~\mathrm{M}\Omega$ 

Insulation Resistance



| Operating Voltage                                       | 250 VAC                     |
|---|-----------------------------|
| Body Features   |                             |
| Daisy Chain   | Without                     |
| Connector Profile                                       | Standard                    |
| Contact Features  |                             |
| Mating Square Post Dimension                            | .64 mm[.025 in]             |
| PCB Contact Termination Area Plating Material Thickness | 2.54 μm[100 μin]            |
| Contact Type  | Pin                         |
|   | 15 μin                      |
| Contact Mating Area Plating Material                    | Gold, Gold Flash            |
| Contact Shape & Form                                    | Square                      |
| Contact Underplating Material                           | Nickel                      |
| PCB Contact Termination Area Plating Material           | Tin-Lead                    |
| Contact Base Material                                   | Brass, Phosphor Bronze      |
| Contact Current Rating (Max)                            | 1 A                         |
| Termination Features                                    |                             |
| Round Termination Post & Tail Diameter                  | .64 mm[.025 in]             |
| Termination Post & Tail Length                          | 2.79 mm[.11 in]             |
| Termination Method to Printed Circuit Board             | Through Hole - Solder       |
| Mechanical Attachment                                   |                             |
| Mating Alignment  | With                        |
| PCB Mount Alignment                                     | Without                     |
| Panel Mount Feature                                     | Without                     |
| PCB Mount Retention                                     | Without                     |
| PCB Mount Retention Type                                | Screw Mount                 |
| Mating Alignment Type                                   | Center, Dual Polarizing Bar |
| Mating Retention  | Without                     |
| Connector Mounting Type                                 | Board Mount                 |
| Housing Features  |                             |
| Housing Material  | Thermoplastic               |
| Housing Color   | Black                       |
| Centerline (Pitch)                                      | 2.54 mm[.1 in]              |
|   |                             |



#### **Dimensions**

| Shrouded End Dimension      | 3.81 mm[.15 in]  |
|-----------------------------|------------------|
| Connector Height            | 13.94 mm[.55 in] |
| PCB Thickness (Recommended) | 1.57 mm[.062 in] |
| Row-to-Row Spacing          | 2.54 mm[.1 in]   |

# **Usage Conditions**

| Housing Temperature Rating  | Standard                   |
|-----------------------------|----------------------------|
| Operating Temperature Range | -65 – 105 °C[-85 – 221 °F] |

# Operation/Application

| Solder Process Feature | Solder Dipped |
|------------------------|---------------|
| Circuit Application    | Signal        |

# **Industry Standards**

| UL Flammability Rating | UL 94V-0 |  |
|------------------------|----------|--|
|------------------------|----------|--|

# **Packaging Features**

| Packaging Quantity | 70   |
|--------------------|------|
| Packaging Method   | Tray |

# **Product Compliance**

For compliance documentation, visit the product page on TE.com>

| EU RoHS Directive 2011/65/EU                  | Not Compliant   |
|---|---|
| EU ELV Directive 2000/53/EC                   | Not Compliant   |
| China RoHS 2 Directive MIIT Order No 32, 2016 | Restricted Materials Above Threshold  |
| EU REACH Regulation (EC) No. 1907/2006        | Current ECHA Candidate List: JAN 2022 (223) Candidate List Declared Against: JAN 2022 (223) SVHC > Threshold: Pb (13% in Component Part) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location. |
| Halogen Content                               | Not Low Halogen - contains Br or Cl > 900 ppm.  |
| Solder Process Capability                     | Wave solder capable to 265°C  |

Product Compliance Disclaimer

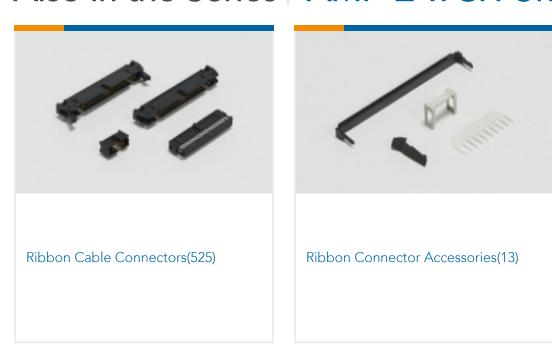


This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

# Compatible Parts



# Also in the Series | AMP-LATCH Universal Headers



# **Customers Also Bought**

















### **Documents**

## **Product Drawings**

020 UNIV HDR SP 4S 15DP STD

English

### **CAD Files**

3D PDF

3D

**Customer View Model** 

ENG\_CVM\_CVM\_102153-4\_M.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_102153-4\_M.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_102153-4\_M.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

# **Product Specifications**

**Product Specification** 

English

# **Product Environmental Compliance**

TE Material Declaration

English

#### **Instruction Sheets**

Instruction Sheet (U.S.)



English

#### AMP INSTALLATION PROCEDURES FOR AMP-LATCH UNIVERSAL HEADER ASSEMBLIE

English

Agency Approvals

Agency Approval Document

English